



Product Change Notification / JAON-18QNOS381

Date:

20-Apr-2023

Product Category:

Broadband Gateway

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5014.004 and 6257 Final Notice: Qualification of a new die size (1.932x1.860mm) for Die #1 of selected Microsemi LE9653AQC, LE9653AQCT, LE9621AQC, LE9643AQC, LE9621AQCT, and LE9643AQCT catalog part numbers (CPN) available in 36L VQFN (4x6x1mm) package assembled at MMT assembly site.

Affected CPNs:

[JAON-18QNOS381_Affected_CPN_04202023.pdf](#)
[JAON-18QNOS381_Affected_CPN_04202023.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of a new die size (1.932x1.860mm) for Die #1 of selected Microsemi LE9653AQC, LE9653AQCT, LE9621AQC, LE9643AQC, LE9621AQCT, and LE9643AQCT catalog part numbers (CPN) available in 36L VQFN (4x6x1mm) package assembled at MMT assembly site.

Pre and Post Change Summary:

		Pre Change					Post Change									
Fabrication Location	Die # 1	Global Foundries, Singapore - Fab 7 (GF07)					Global Foundries, Singapore - Fab 7 (GF07)									
	Die # 2	Global Foundries, Singapore - Fab 2 (GF02)			Microchip Technology Colorado – Fab 5 (MCSO)		Global Foundries, Singapore - Fab 2 (GF02)		Microchip Technology Colorado – Fab 5 (MCSO)							
Die Size	Die # 1	2.204 x 2.258 mm					1.932x1.860mm									
	Die # 2	Please see attached pre and post change comparison for Die # 1 Location					1.57 x 1.72 mm									
Assembly Site		Microchip Technology Thailand (Branch) (MMT)					Microchip Technology Thailand (Branch) (MMT)									
Wire Material		CuPdAu					CuPdAu									
Die Attach Material		3280					3280									
Molding Compound Material		G700LTD					G700LTD									
Lead Frame Material		A194					A194									

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity by qualifying a new die size.

Change Implementation Status:In Progress

Estimated First Ship Date:May 5, 2023 (date code: 2318)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	May 2022					>	April 2023					May 2023				
	1 9	2 0	2 1	2 2	2 3		1 3	1 4	1 5	1 6	1 7	1 8	1 9	2 0	2 1	2 2
Initial PCN Issue Date				X												
Qual Report										X						

Availability												
Final PCN Issue Date							X					
Estimated Implementation Date								X				

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:May 24, 2022: Issued initial notification.

April 20, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on May 5, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-18QNOS381_Qual_Report.pdf](#)

[PCN_JAON-18QNOS381 Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to [receive Microchip PCNs via email](#) please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to [change your PCN profile, including opt out](#), please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.